Prototype Lab Flow Project

Projects website: https://mndkoo76.github.io/

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Proposal

Proposal for the Prototype Lab Flow Project

Prepared by Kenneth Mendoza and Sukhdeep Sehra Computer Engineering Technology Student https://mndkoo76.github.io/

Executive Summary

As a student in the Computer Engineering Technology program, I will be integrating the knowledge and skills I have learned from our program into this Internet of Things themed capstone project. This proposal requests the approval to build the hardware portion that will connect to a database as well as to a mobile device application. The Internet connected hardware will include a custom PCB with sensors and actuators for LCD monitor and a scanner. The database will store all of the items from the parts crib for availability of the parts, and all of the users and admins info from the mobile app. The mobile device functionality will include a mobile app for users to request items, a LCD monitor that display the users requested items, a scanner to scan the user mobile app when returning the items, a mobile app for the users to send request items and will be further detailed in the mobile application proposal. I will be collaborating with Humber College Technology Department. In the winter semester I plan to form a group with the following students; Sukhdeep Sehra and Mathues Rondinelli, who are also building similar hardware this term and working on the mobile application with me. The hardware will be completed in CENG 317 Hardware Production Techniques independently and the application will be completed in CENG 319 Software Project. These will be integrated together in the subsequent term in CENG 355 Computer Systems Project as a member of a 2 or 3 student group.

Background

The problem solved by this project is to make the parts crib more organized and operate smoother than ever before. As of now we know the parts crib function; student line up to write the items they may need and give their student ID with the requested items then the worker from the crib get the requested items one by one. This functionality takes up time, waste paper and pen. Students sometimes wait for awhile in the line and find out there's no more parts available. Our project will enhance the parts crib functionality by making a mobile app that a student can send request items from their phone while still in classroom or before their lab starts and that request will be send to the parts crib LCD monitor that the worker can see and start preparing the items for the student. The worker will then send a notification to the student that his/her requested parts are ready to be pick up. After the student used the parts he/she returns the items in the crib, the worker will scan the student mobile app to see what items the student borrow. This project will eliminate student lining up, giving out their student ID, using paper and pen to request an item and student will know if the parts are still available and when it's ready to be pick up. Overall, the parts crib will save time and money and it's going to be more convenient with everyone.

I have searched for prior art via Humber's IEEE subscription selecting "My Subscribed Content"[1] and have found and read [2] which provides insight into similar efforts.

The first article discusses how Gabor used QR decomposition for image encoding. [@250340]

The second article discusses how support system for QR codes based educational processes. [@7036011]

The third article discusses how VLSI implementation of hybrid QR code generation system. [@6892829]

In the Computer Engineering Technology program we have learned about the following topics from the respective relevant courses:

- Java Docs from CENG 212 Programming Techniques In Java,
- Construction of circuits from CENG 215 Digital And Interfacing Systems,
- Rapid application development and Gantt charts from CENG 216 Intro to Software Engineering,
- Micro computing from CENG 252 Embedded Systems,
- SQL from CENG 254 Database With Java,
- Web access of databases from CENG 256 Internet Scripting; and,
- Wireless protocols such as 802.11 from TECH152 Telecom Networks.

This knowledge and skill set will enable me to build the subsystems and integrate them together as my capstone project.

Methodology

This proposal is assigned in the first week of class and is due at the beginning of class in the second week of the fall semester. My coursework will focus on the first two of the 3 phases of this project:

Phase 1 Hardware build.

Phase 2 System integration.

Phase 3 Demonstration to future employers.

Phase 1 Hardware build

The hardware build will be completed in the fall term. It will fit within the CENG Project maximum dimensions of $12\ 13/16$ " x 6" x $2\ 7/8$ " (32.5cm x 15.25cm x 7.25cm) which represents the space below the tray in the parts kit. The highest AC voltage that will be used is 16Vrms from a wall adaptor from which $+/-\ 15$ V or as high as 45 VDC can be obtained. Maximum power consumption will be 20 Watts.

Phase 2 System integration

The system integration will be completed in the fall term.

Phase 3 Demonstration to future employers

This project will showcase the knowledge and skills that I have learned to potential employers.

The tables below provide rough effort and non-labour estimates respectively for each phase. A Gantt chart will be added by week 3 to provide more project schedule details and a more complete budget will be added by week 4. It is important to start tasks as soon as possible to be able to meet deadlines.

Labour Estimates	Hrs	Notes
Phase 1		
Writing proposal.	9	Tech identification quiz.
Creating project schedule. Initial project	9	Proposal due.
team meeting.		
Creating budget. Status Meeting.	9	Project Schedule due.
Acquiring components and writing	9	Budget due.
progress report. Mechanical assembly and writing progress report. Status Meeting.	9	Progress Report due (components acquired milestone).
PCB fabrication.	9	Progress Report due (Mechanical Assembly milestone).
Interface wiring, Placard design, Status Meeting.	9	PCB Due (power up milestone).
Preparing for demonstration.	9	Placard due.
Writing progress report and demonstrating project.	9	Progress Report due (Demonstrations at Open House Saturday, November 7, 2015 from 10 a.m 2 p.m.).

Editing build video. Incorporation of feedback from demonstration and writing progress report. Status Meeting.	9	Peer grading of demonstrations due. 30 second build video due.
Practice presentations	9	Progress Report due.
1st round of Presentations, Collaborators	9	Presentation PowerPoint file due.
present.	9	resentation rowerrount me due.
2nd round of Presentations	9	Build instructions up due.
Project videos, Status Meeting.	9	30 second script due.
Phase 1 Total	135	go become soript due.
Phase 2	-00	
Meet with collaborators	9	Status Meeting
Initial integration.	9	Progress Report
Meet with collaborators	9	Status Meeting
Testing.	9	Progress Report
Meet with collaborators	9	Status Meeting
Meet with collaborators	9	Status Meeting
Incorporation of feedback.	9	Progress Report
Meet with collaborators	9	Status Meeting
Testing.	9	Progress Report
Meet with collaborators	9	Status Meeting
Prepare for demonstration.	9	Progress Report
Complete presentation.	9	Demonstration at Open House Saturday,
		April 9, 2016 10 a.m. to 2 p.m.
Complete final report. 1st round of Presentations.	9	Presentation PowerPoint file due.
Write video script. 2nd round of	9	Final written report including final budget
Presentations, delivery of project.		and record of expenditures, covering both this semester and the previous semester.
Project videos.	9	Video script due
Phase 2 Total	135	
Thase 2 Total		
Phase 3		
Phase 3 Interviews	TBD	
Phase 3 Interviews Phase 3 Total	TBD TBD	
Phase 3 Interviews Phase 3 Total Material Estimates	TBD	Notes
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Phase 3 Interviews Phase 3 Total Material Estimates Phase 1 A microcomputer composed of a	TBD TBD	Notes An example of a retailer: [3].
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Shipping	TBD	
Tax	TBD	
Duty	TBD	
Phase 3 Total	TBD	

Concluding remarks

This proposal presents a plan for providing an IoT solution for *Future Humber Quadcopter Swarm*. This is an opportunity to integrate the knowledge and skills developed in our program to create a collaborative IoT capstone project demonstrating my ability to learn how to support projects such as the initiative described by [3]. I request approval of this project.

References